Appl. No.: 10/534,617

Docket No.: DB001183-000

Amdt. Dated: 6/19/2009

Reply to Office action of 02/27/2009

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended)

A method of manufacturing a security thread or strip introduceable in banknotes, said security

thread or strip having a microchip, comprising the steps of:

providing a support material on a substrate to form a thread or strip;

softening said support material, preferably by heating said support material;

depositing a microchip on or at least partly in the softened support material; and

curing said support material, preferably by cooling said support material.

Claim 2 (previously amended)

The method of manufacturing a security thread according to claim 1, wherein said support

material is a heat-sensitive material, preferably a thermoplastic material containing a resin having a low

melting point, such as wax, vinyl-polymer, polyurethane or any polymer or compound distributed in

water based solvents or in any solvent that has the characteristics to modify its state from solid to soft.

Claim 3 (previously amended)

The method of manufacturing a security thread according to claim 1, wherein, in the step of

softening said support material, the support material is heated by contact with a heating means or by heat

radiation, preferably by an infrared beam, and ultraviolet beam or laser beam.

Claim 4 (previously amended)

The method of manufacturing a security thread according to claim 1, wherein, in the step of

depositing said microchip, the microchip falls on the softened support material and sinks at least partly

into the support material by its own gravity.

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Claim 5 (previously amended)

The method of manufacturing a security thread according to claim 1, wherein, in the step of

depositing said support chip, said microchip is positioned on the support material, and thereafter, when

the support material is still soft, the microchip is pressed into the support material by a pressing means.

Claim 6 (previously amended)

The method of manufacturing a security thread according to claim 1, comprising a step of

winding up the security thread around a spool.

Claim 7 (previously amended)

The method of manufacturing a security thread according to claim 6, wherein a timing of

softening said support material, depositing said microchip and/or curing said support material is set in

accordance to a winding operation of the spool.

Claim 8 (previously amended)

The method of manufacturing a security thread according to claim 6 or claim 7, wherein said

spool is a watermarking cylinder which has register notches and transports the security thread into a paper

compound, and said timing of softening said support material, depositing said microchip and/or curing

said support material is set in accordance to a detection of said register notches.

Claim 9 (currently amended)

A security thread introduceable in banknotes comprising

a substrate, preferably of polyester;

a support material provided on the substrate to form a thread,

characterized by

a microchip fixedly attached to or at least partly embedded in the support material.

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Claim 10 (previously amended)

The security thread according to claim 9, wherein the support material is a heat-sensitive material.

Claim 11 (previously amended)

The security thread according to claim 9, wherein the support material comprises an adhesive or

glue material which is preferably permanently active.

Claim 12 (previously amended)

The security thread according to claim 10 or claim 11, wherein a siliconated layer is removably

deposited on the adhesive or glue material, or wherein a siliconated layer is deposited on the side of the

thread which is opposite to the adhesive or glue material.

Claim 13 (previously amended)

The security thread according to claim 9, wherein the microchip comprises an antenna for contactless data

transfer.

Claim 14 (currently amended)

A security thread introduceable in banknotes comprising,

a substrate, preferably of polyester,

a support material provided on the substrate to form a thread, and

a medium layer which carries specific characters, signs, holograms, data or any other information

on a magnetic medium, metallic medium, fluorescent medium, printed medium or any other medium,

wherein the medium layer is preferably located between the substrate and the support material.

Claim 15 (previously amended)

A document, preferably a paper document, comprising said security thread according to claim 9

or claim 14.

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